PCN Number:			1911170			PCN Date:			Nov. 22, 2019			
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Cu	stom	er Contact:	<u>PCI</u>	<u> Manag</u>	<u>er</u>					pt:	Quality Services	
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						Design				Wafer Bump Site		
Щ		embly Process			$\boxtimes$				<u>Щ</u>	Wafer Bump Material		
Assembly Materials					Щ	Part number change			<u> </u>	Wafer Bump Process		
Mechanical Specifica					Н	Test Site					er Fab Site	
Packing/Shipping/Labeling					Test Proce	est Process			Wafer Fab Materials Wafer Fab Process			
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C	Change	s from Revision A	(Febr	ruary 2018	) to R	levision B					Page	
Added the QFN Package to the Features section								1				
	Added Package QFN (16) and Body Size 4.00 mm × 3.5 mm to the Device Information table											
	Updated the Typical Application Schematic											
	Added RRK Package to the Pin Out Drawing and Pin Functions table											
	Updated the Specifications Absolute Maximum Ratings table											
•	Changed the Operation junction temperature range MAX from 150°C to 125°C in the Specifications Recommended											
	Operating Conditions table											
•	Added RRK package to the Specifications Thermal Information table											
•	Updated the Operating Current section in the Specifications Electrical Characteristics table											
The datasheet number will be changing.								ao Tor				
Device Family						Change	Change From:			Change To:		
TPS27S100				SLVSE4	SLVSE42A			SLVSE42B				
These changes may be reviewed at the datasheet links provided.												
http://www.ti.com/product/TPS27S100												
Reason for Change:												
To accurately reflect device characteristics.												
		•					uality or Reli	abi	ility	y (po	sitive / negative):	
No anticipated impact. This is a specification change announcement only. There are no changes												
to the actual device.												
Changes to product identification resulting from this PCN:  None.												
Product Affected:  TPS27S100APWPR  TPS27S100APWPT  TPS27S100APRKT  TPS27S100APRKT												
			T	PS27S1	00A	PWPT	TPS27S10	OAF	RRK	(R	TPS27S100ARRKT	
	TPS27S100BPWPR TPS27S100I			00B	PWPT TPS27S100			RRK	(R	TPS27S100BRRKT		

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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